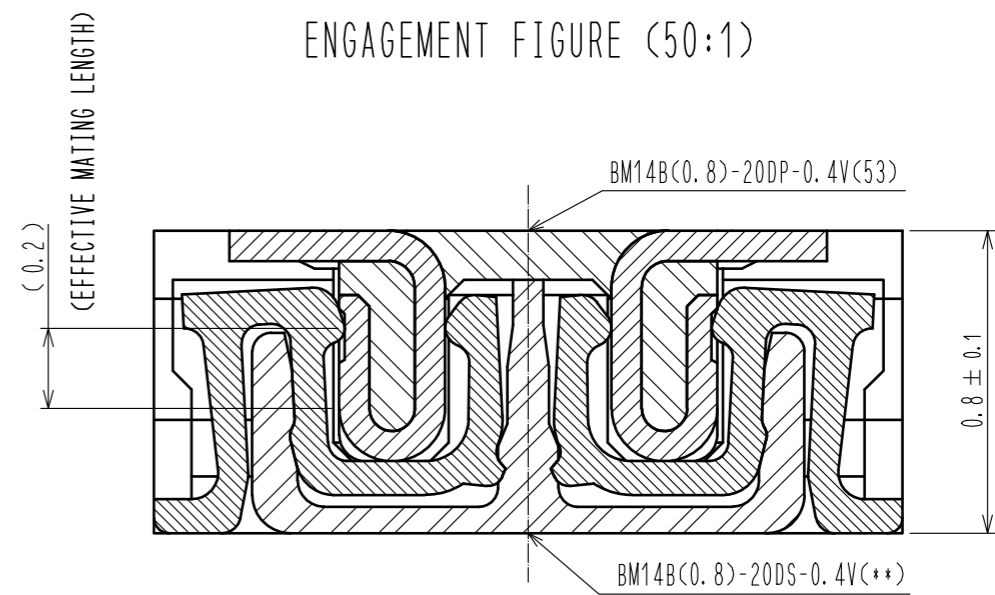
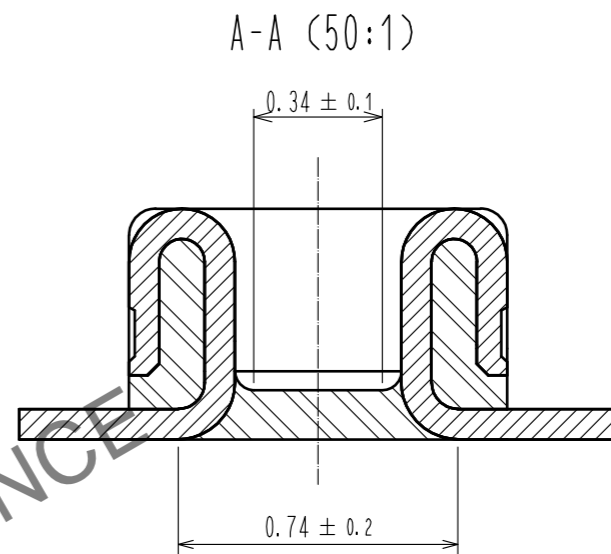
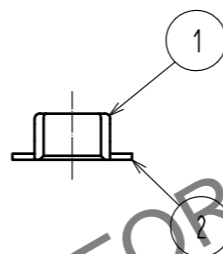
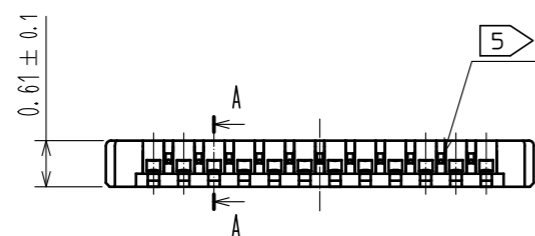
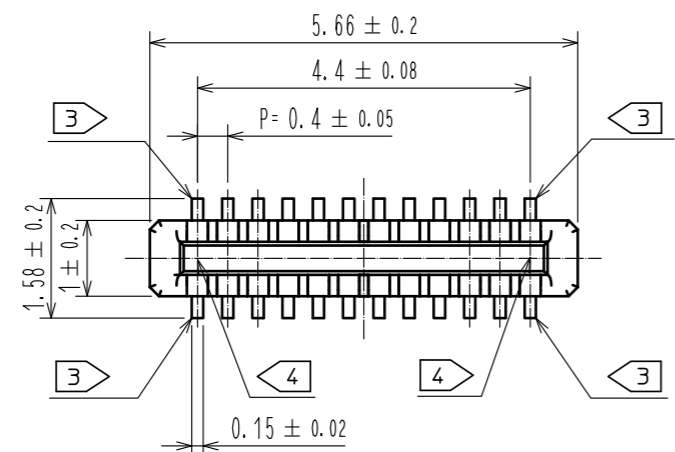


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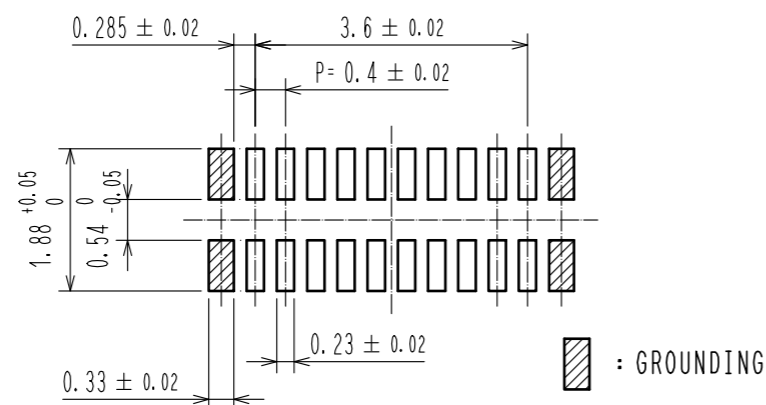


- NOTE) 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
- 2 . CONTACT PLATING SPECIFICATIONS
 CONTACT AREA : GOLD 0.05 μm MIN
 SMT LEAD : GOLD 0.05 μm MIN
 UNDERPLATING : NICKEL 1 μm MIN
 (SURFACE : SEALING)
- 3 . EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS AND GROUNDING PURPOSE.
- 4 . HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
- 5 . A PART OF THE WALL COULD BE NOTCHED.

3	PS	CLEAR (ENBOSSED CARRIER TAPE)	6	PS	CLEAR (REINFORCEMENT COLLAR)			
2	PHOSPHOR BRONZE	2	5	PS	BLACK (PLASTIC REEL)			
1	LCP	UL94 V-0, BLACK	4	POLYESTER	CLEAR (COVER TAPE)			
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS			
UNITS	mm	SCALE	10 : 1	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
HRS HIROSE ELECTRIC CO., LTD.		APPROVED : MO. ISHIDA	17.01.19	DRAWING NO. EDC-319846-53-00				
		CHECKED : TS. MIYAZAKI	17.01.19	PART NO. BM14B(0.8)-20DP-0.4V(53)				
		DESIGNED : NY. YAMASHIRO	17.01.19	CODE NO. CL684-8011-3-53				
		DRAWN : SN. NUMAZAKI	17.01.18					

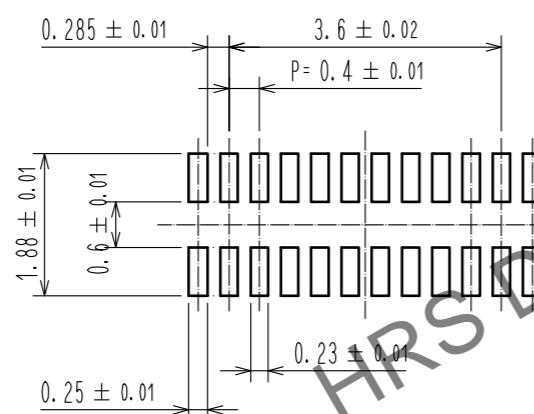
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◆ RECOMMENDED PCB LAYOUT

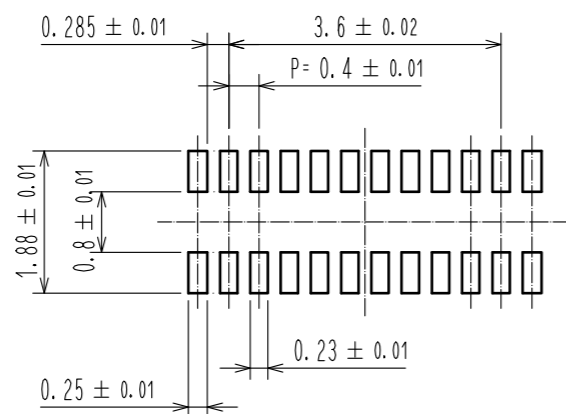


◆ RECOMMENDED METAL MASK DIMENSIONS

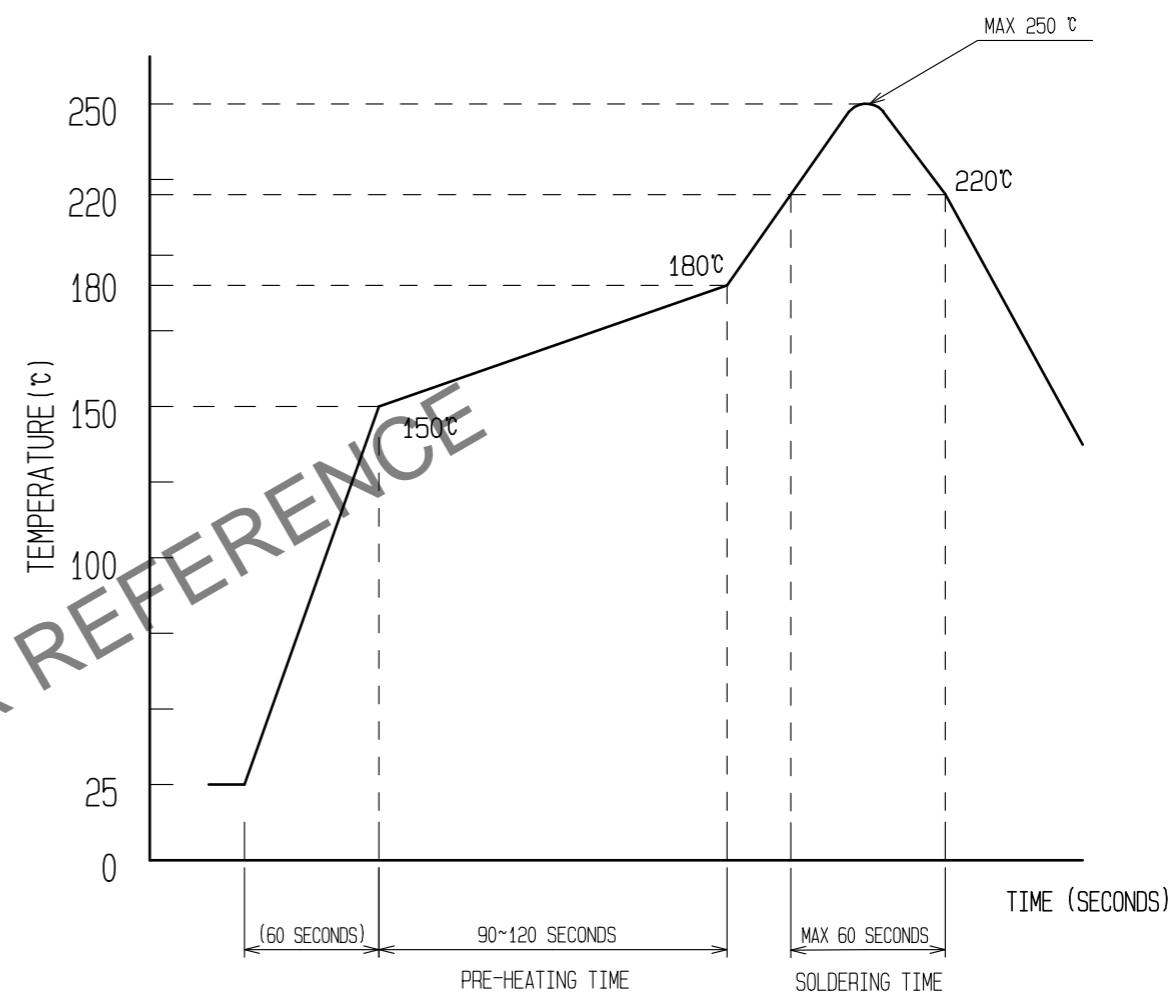
METAL MASK THICKNESS : 100 μm



METAL MASK THICKNESS : 120 μm



⑥ RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



- REFLOW METHOD: IR REFLOW
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
- 1) REFLOW TIME
 DURATION ABOVE 220°C, 60 SEC. MAX.
 (PEAK TEMPERATURE: 250°C MAX)
 - 2) PRE-HEAT TIME
 PRE-HEAT TEMPERATURE(MIN): 150°C
 PRE-HEAT TEMPERATURE(MAX): 180°C
 PRE-HEAT TIME: 90-120 sec.

⑥ THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS	DRAWING NO.	EDC-319846-53-00	
	PART NO.	BM14B(0.8)-20DP-0.4V(53)	
	CODE NO.	CL684-8011-3-53	②/3

